

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20180111006 Datasheet for SN74LVC1G06 Information Only

Date: January 12, 2018

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE SN74LVC1G06DCKR SN74LVC1G06DRYR

SN74LVC1G06DCKT

CUSTOMER PART NUMBER

null null null

Technical details of this Product Change follow on the next page(s).

20			2018	20180111006			PCN Date: January			ary 12	12, 2018	
Title: Datasheet for SN74LVC1G06												
Cu	stome	er Contact:	PCN M	<u>lanager</u>	•			Dept:			: Quality Services	
Change Type:												
	Assembly Site			Design							r Bump Site	
<u>Ц</u>	Assembly Process				=	Data Sheet			<u>Ц</u>		r Bump Material	
Assembly Materials					_	Part number change			<u> </u>	Wafer Bump Process		
	Mechanical Specification			_	_	Test Site					r Fab Site	
Packing/Shipping/Label			Labelin	g L		Test Process			<u>Щ</u>		r Fab Materials	
Notification Details Wafer Fab Proc											I Fab Process	
Do	ccrint	ion of Chang	101	<u>_</u>	101	liiicatic	n Details					
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. Texas Instruments SN74LVC1G06												
SCES295Z – JUNE 2000 – REVISED NOVEMBER 2017												
Changes from Revision Y (February 2017) to Revision Z												
Changed values in the Thermal Information table to align with JEDEC standards												
The datasheet number will be changing.												
Device Family				Change			From:			Change To:		
SN74LVC1G06					SCES295Y				SCES295Z			
The	ese cha	anges may be	review	ed at t	he d	datasheet	: links provide	d.				
http://www.ti.com/product/SN74LVC1G06												
Re	ason f	for Change:										
То	accura	tely reflect de	evice us	sage in	spe	cific appl	ication use ca	ses				
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a recommendation change to application circuit only. There are no changes to the actual device.												
Changes to product identification resulting from this PCN:												
None.												
Pro	oduct	Affected:										
SI	N74LVC	1G06DBVR	SN74	SN74LVC1G06DC			SN74LVC1G06DCKT			4 S	N74LVC1G06DSFR	
SI	N74LVC	1G06DBVRE4	5DBVRE4 SN74LVC1G06D)6D(CKRE4 SN74LVC1G06DF			RLR S		N74LVC1G06YZPR	
SI	N74LVC	C1G06DBVRG4 SN74LVC1G06D0			CKRG4	SN74LVC1G06DRY2				N74LVC1G06YZVR		
SI	N74LVC1G06DBVT SN74LVC1G06D0			CKT	SN74LVC1G06DRYR							
SN	SN74LVC1G06DBVTG4 SN74LVC1G06DCK				CKTE4	SN74LVC1G06DSF2						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com